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June 2014

FDMD82100

Dual N-Channel Power Trench[®] MOSFET 100 V, 25 A, 19 m Ω

Features

- Max $r_{DS(on)}$ = 19 m Ω at V_{GS} = 10 V, I_D = 7 A
- Max $r_{DS(on)} = 33 \text{ m}\Omega$ at $V_{GS} = 6 \text{ V}$, $I_D = 5.5 \text{ A}$
- Ideal for flexible layout in primary side of bridge topology
- Termination is Lead-free and RoHS Compliant
- 100% UIL tested
- Kelvin High Side MOSFET drive pin-out capability

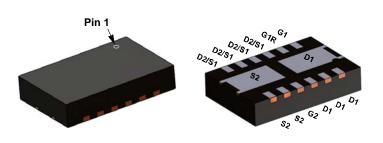


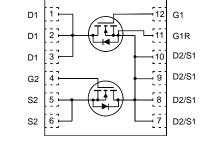
General Description

This device includes two 100V N-Channel MOSFETs in a dual Power (3.3 mm X 5 mm) package. HS source and LS Drain internally connected for half/full bridge, low source inductance package, low r_{DS(on)}/Qg FOM silicon.

Applications

- Synchronous Buck : Primary Switch of Half / Full bridge converter for telecom
- Motor Bridge: Primary Switch of Half / Full bridge converter for BLDC motor
- MV POL: 48V Synchronous Buck Switch





Power 3.3 x 5

MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parame	eter		Ratings	Units
V _{DS}	Drain to Source Voltage			100	V
V _{GS}	Gate to Source Voltage			±20	V
I _D	Drain Current -Continuous	T _C = 25 °C		25	
	-Continuous	T _A = 25 °C	(Note 1a)	7	Α
	-Pulsed		(Note 4)	80	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	121	mJ
D	Power Dissipation	T _A = 25 °C	(Note 1a)	2.1	w
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1b)	1	VV
T _J , T _{STG}	Operating and Storage Junction Tempera	ture Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case		3.1	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	60	°C/W
R _{0,JA}	Thermal Resistance, Junction to Ambient	(Note 1b)	130	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
82100	FDMD82100	Power 3.3 x 5	13 "	12 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		70		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μА
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2	3.3	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-9		mV/°C
		V _{GS} = 10 V, I _D = 7 A		15	19	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 6 \text{ V}, I_D = 5.5 \text{ A}$		23	33	mΩ
` '		$V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}, T_J = 125 ^{\circ}\text{C}$		27	35	
9 _{FS}	Forward Transconductance	$V_{DD} = 5 \text{ V}, I_{D} = 7 \text{ A}$		18		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 50 V V 0 V		805	1070	pF
Coss	Output Capacitance	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}$ f = 1 MHz		176	235	pF
C _{rss}	Reverse Transfer Capacitance	1 = 1 101112		8	15	pF
R_{α}	Gate Resistance		0.1	1.8	3.6	Ω

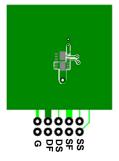
Switching Characteristics

	•					
t _{d(on)}	Turn-On Delay Time			9.4	19	ns
t _r	Rise Time	V _{DD} = 50 V, I _D = 7 A		3.2	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, R _{GEN} =	6 Ω	15	27	ns
t _f	Fall Time			3.3	10	ns
0	Total Gate Charge	V _{GS} = 0 V to 10 V		12	17	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to 6 V}$	_{DD} = 50 V	8	11	nC
Q _{gs}	Gate to Source Charge	ال) = 7 A	3.9		nC
Q_{qd}	Gate to Drain "Miller" Charge			2.7		nC

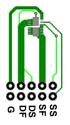
Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 7 \text{ A}$	(Note 2)	0.8	1.2	V
t _{rr}	Reverse Recovery Time	I _E = 7 A, di/dt = 100 A/μs		46	74	ns
Q _{rr}	Reverse Recovery Charge	$F = I A$, $ai/at = 100 A/\mu s$		48	77	nC

^{1.} $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 60 °C/W when mounted on a 1 in² pad of 2 oz copper



b. 130 °C/W when mounted on a minimum pad of 2 oz copper

^{2.} Pulse Test: Pulse Width < 300 $\mu s,$ Duty cycle < 2.0 %.

^{3.} E_{AS} of 121 mJ is based on starting T_J = 25 °C, L = 3 mH, I_{AS} = 9 A, V_{DD} = 100 V, V_{GS} = 10 V. 100% tested at L = 0.1 mH, I_{AS} = 30 A.

^{4.} Pulse Id refers to Figure.11 Forward Bias Safe Operation Area.

Typical Characteristics T_J = 25 °C unless otherwise noted

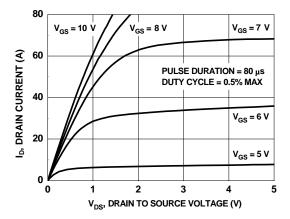


Figure 1. On Region Characteristics

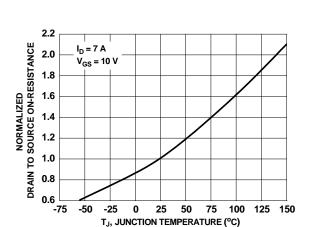


Figure 3. Normalized On Resistance vs Junction Temperature

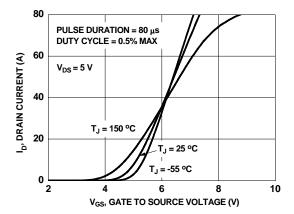


Figure 5. Transfer Characteristics

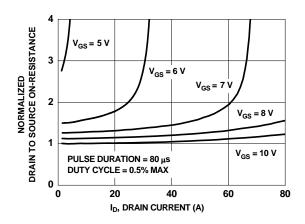


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

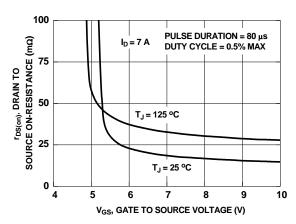


Figure 4. On-Resistance vs Gate to Source Voltage

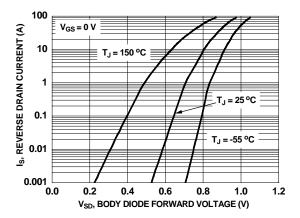


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

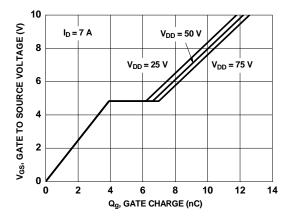
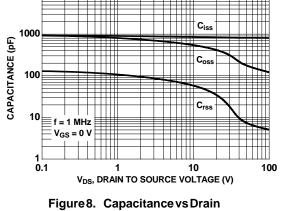


Figure 7. Gate Charge Characteristics



10000

to Source Voltage

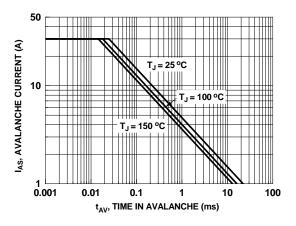


Figure 9. Unclamped Inductive **Switching Capability**

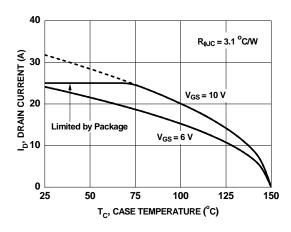


Figure 10. Maximum Continuous Drain **Current vs Case Temperature**

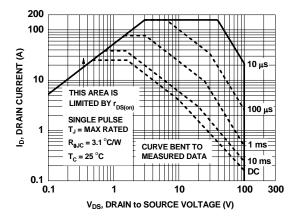


Figure 11. Forward Bias Safe **Operating Area**

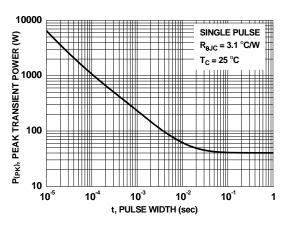


Figure 12. Single Pulse Maximum **Power Dissipation**

Typical Characteristics $T_J = 25$ °C unless otherwise noted

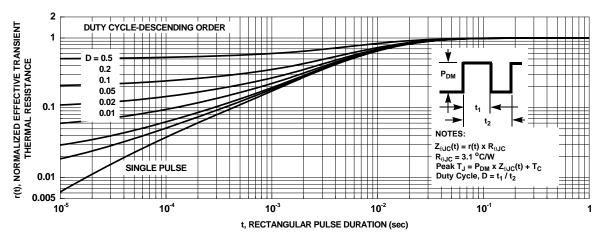
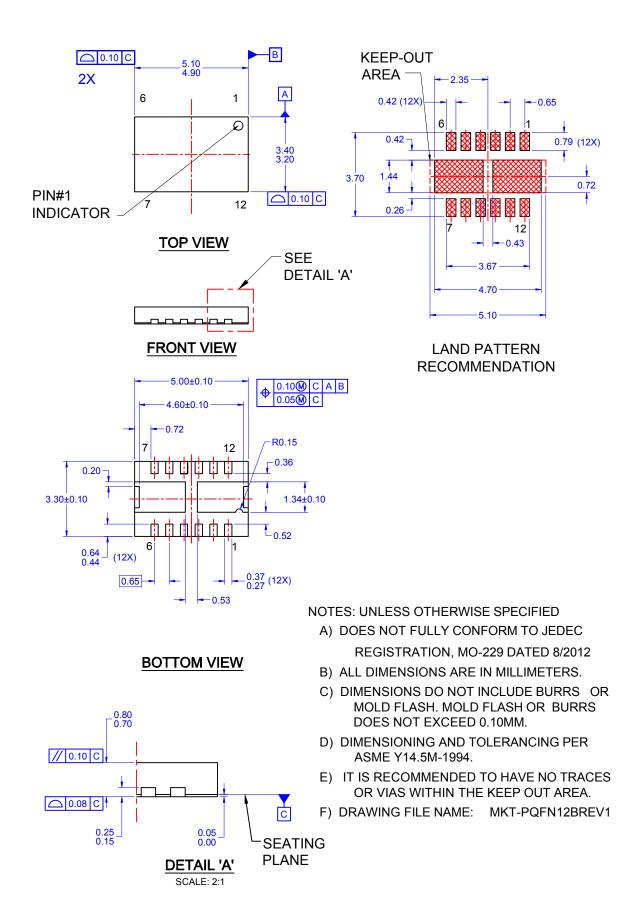


Figure 13. Junction-to-Case Transient Thermal Response Curve



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